PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5491990

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
PEI-YU WANG	03/29/2019
ZHI-CHANG LIN	03/29/2019
CHING-WEI TSAI	03/29/2019
KUAN-LUN CHENG	03/29/2019

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	
Street Address:	8, LI-HSIN RD. 6	
Internal Address:	HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	300-78	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16366511

CORRESPONDENCE DATA

Fax Number: (214)200-0853

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 214-651-5000

Email: ipdocketing@haynesboone.com

Correspondent Name: HAYNES AND BOONE, LLP IP SECTION

Address Line 1: 2323 VICTORY AVENUE

Address Line 2: SUITE 700

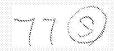
Address Line 4: DALLAS, TEXAS 75219

ATTORNEY DOCKET NUMBER:	2018-1216/24061.3783US01
NAME OF SUBMITTER:	MARCY OGADO
SIGNATURE:	/Marcy Ogado/
DATE SIGNED:	04/25/2019

Total Attachments: 2

PATENT REEL: 048992 FRAME: 0862 source=3783US01_Assignment#page1.tif source=3783US01_Assignment#page2.tif

PATENT REEL: 048992 FRAME: 0863



Docket No.: P20181216US00/24061.3783US01 Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

(1)	Pei-Yu Wang	of Hsinchu City, Taiwan (R.O.C.)
(2)	Zhi-Chang Lin	of Hsinchu County, Taiwan (R.O.C.
(3)	Ching-Wei Tsai	of Hsinchu City, Taiwan (R.O.C.)
(4)	Kuan-Lun Cheng	of Hsin-Chu, Taiwan (R.O.C)

have invented certain improvements in

METHOD FOR METAL GATE CUT AND STRUCTURE THEREOF

for which we have executed an application for Letters Patent of the United States of America,

X of even date filed herewith; and filed on 03/27/2019 and assigned application number 16/366,511; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filling date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal,

4816-1966-3433 v.1 - 1 -

Docket No.: P20181216US00/24061.3783US01

Customer No.: 000042717

substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Pei-Yu Wang Residence Address: Hsinchu City, Taiwan (R.O.C.) Pei - 74 Wang Inventor Signature Dated: 2019 3 2 9 Inventor Name: Zhi-Chang Lin Residence Address: Hsinchu County, Taiwan (R.O.C.) 24 44 45 Inventor Signature Dated: 2015 03. 2/ Ching-Wei Tsai Inventor Name: Residence Address: Hsinchu City, Taiwan (R.O.C.) Inventor Name: Kuan-Lun Cheng Residence Address: Hsin-Chu, Taiwan (R.O.C.) Dated: 2019, 3, 29

-2-

4816-1906-3433 v.1